

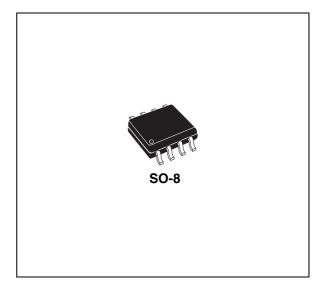
## High voltage high-side driver

#### **Features**

- High voltage rail up to 450 V
- dV/dt immunity ±50 V/nsec in full temperature range
- Driver current capability: 500 mA source, 500 mA sink
- Switching times 100 ns rise/fall with 2.5 nF load
- CMOS/TTL Schmitt trigger inputs with hysteresis and pull down
- Under voltage lock out
- Clamping on V<sub>CC</sub>
- Non inverting input
- Reset circuitry
- SO8 package

### **Description**

The L9857 is an high voltage device, manufactured with the BCD "off-line" technology.



It has the capability of driving N channel PowerMOS transistors. The upper (floating) section is enabled to work with voltage rail up to 450 V. The logic inputs are CMOS/TTL compatible for ease of interfacing with controlling devices..

Table 1. Device summary

Order code	er code Op. temp range, °C Package		Packing
L9857-TR	-40 to +125	SO-8	Tape and reel
L9857-TR-LF	-40 to +125	SO-8	Tape and reel

Content L9857

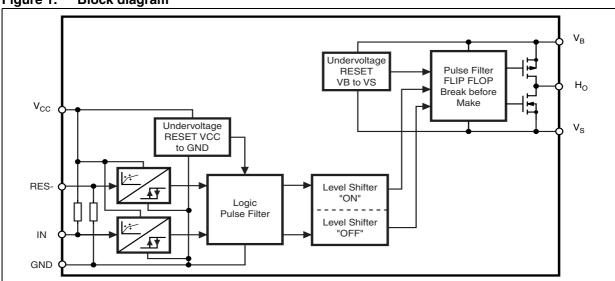
## Content

1	Bloc	k diagram and pin description
	1.1	Block diagram
	1.2	Pin description
2	Elec	trical specifications 4
	2.1	Thermal data 4
	2.2	Absolute maximum ratings
	2.3	Recommended operating conditions 5
	2.4	Electrical characteristics
	2.5	Reset functional diagram 7
3	Timi	ng diagrams 8
4	Pack	rage information
5	Revi	sion history10

## 1 Block diagram and pin description

#### 1.1 Block diagram

Figure 1. Block diagram



## 1.2 Pin description

Figure 2. Pin connection (top view)

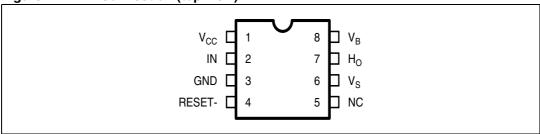


Table 2. Pin function

Pin #	Pin name	Description	
1	V <sub>CC</sub>	Driver supply, typically 17V	
2	IN	Driver control signal input (positive logic)	
3	GND	Ground	
4	RESET-	Driver enable signal input (negative logic)	
5	NC	No connection (no bondwire)	
6	V <sub>S</sub>	MOSFET source connection	
7	H <sub>O</sub>	MOSFET gate connection	
8	V <sub>B</sub>	Driver output stage supply	

## 2 Electrical specifications

#### 2.1 Thermal data

Table 3. Thermal data

Symbol	Parameter	Value	Unit
R <sub>th(j-amb)</sub>	Thermal resistance junction-to-ambient Max.	150	°C/W

#### 2.2 Absolute maximum ratings

Absolute maximum ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to GND, all currents are defined positive into any lead. This is a stress only rating and operation of the device at these or any conditions exceeding those indicated in the operational sections of this specifications is not implied.

Table 4. Absolute maximum ratings

	Parameter	Va	Units		
Symbol	Definition	Min.	Max.	Units	
V <sub>BS</sub>	High side floating supply voltage	-0.3	20	V	
V <sub>B</sub>	High side driver output stage voltage	-0.3	300	V	
V <sub>S</sub>	High side floating supply offset voltage	V <sub>B</sub> – 20	300	V	
VH <sub>O</sub>	Output voltage gate connection	V <sub>S</sub> - 0.3	V <sub>B</sub> + 0.3	V	
V <sub>CC</sub>	Supply voltage	-0.3	20	V	
V <sub>IN</sub>	Input voltage	-0.3	V <sub>CC</sub> + 0.3	V	
I <sub>IN</sub>	Input injection current. Full function, no latch-up; (guaranteed by design). Test at 10 V and 17 V on eng. samples.	-	+1	mA	
V <sub>RES</sub>	Reset input voltage	-0.3	V <sub>CC</sub> + 0.3	V	
V <sub>esd</sub>	Electrostatic discharge voltage (human body model)	2k	-	V	
V <sub>CDM</sub>	Charge device model CDM, EOS/ESD ass. std 5.3. number of discharges per pin: 6	500	-	V	
dV/dt	Allowable offset voltage slew rate	-50	50	V/nsec	
Tj	Junction temperature	-55	150		
T <sub>stg</sub>	Storage temperature	-55	150		
TL	Lead temperature (soldering, 10 seconds) 3 times Bosch soldering profil acc. to Bosch soldering conditions, gen. spec.	-	300	°C	

#### 2.3 Recommended operating conditions

For proper operations the device should be used within the recommended conditions.

Table 5. Recommended operating conditions

	Parameter	Val	Units	
Symbol	Definition	Min.	Max.	Units
V <sub>B</sub>	High side driver output stage voltage -5 V transient 0.1µs	VS+10 <sup>(1)</sup>	VS+18	V
V <sub>S</sub>	High side floating supply offset voltage - 20 V transient 0.1µs	-5	300	V
V <sub>HO</sub>	Output voltage gate connection	V <sub>S</sub>	V <sub>B</sub>	V
V <sub>CC</sub>	Supply voltage	10	18	V
V <sub>IN</sub>	Input voltage	0	V <sub>CC</sub>	V
V <sub>RES</sub>	Reset input voltage	0	V <sub>CC</sub>	V
F <sub>S</sub>	Switching frequency	-	200	kHz
T <sub>amb</sub>	Ambient temperature	-40	125	°C

<sup>1.</sup> Reset-Logic functional for  $V_B$ - $V_S$ =2V, independent from VCC-level

#### 2.4 Electrical characteristics

Unless otherwise specified, V<sub>CC</sub> = 15 V, V<sub>BS</sub> = 15 V, V<sub>S</sub> = 0 V, IN = 0 V, RES = 5 V, load R = 50  $\Omega$ , C = 2.5 nF. Unless otherwise noted, these specifications apply for an operating junction temperature range of -40 °C  $\leq$  T<sub>j</sub>  $\leq$  125 °C

Table 6. Electrical characteristics

Symbol	Parameter	Test condition	Min.	Тур.	Max.	Unit
V <sub>CC</sub> supply						
V <sub>CCUV</sub>	V <sub>CC</sub> supply undervoltage	V <sub>CC</sub> rising from 0 V V <sub>CC</sub> dropping from 10 V	7.2	-	9.6	V
V <sub>CCUVHYS</sub>	V <sub>CC</sub> supply undervoltage lockout hysteresis	-	0.02	0.2	0.4	V
td <sub>UVCC</sub>	Undervoltage lockout response time	V <sub>CC</sub> steps either from 10 V to 6 V or from 6 V to 10 V	0.5	-	20	μS
I <sub>QCC</sub>	V <sub>CC</sub> supply current	-	-	-	400	μΑ
V <sub>BS</sub> supply						
V <sub>BSUV</sub>	V <sub>BS</sub> supply undervoltage	V <sub>BS</sub> rising from 0 V V <sub>BS</sub> dropping from 10 V	7.2	-	9.6	V
td <sub>UVBS</sub>	Undervoltage lockout response time	V <sub>BS</sub> steps either from 10 V to 6 V or from 6 V to 10 V	0.5	-	20	μS

Table 6. Electrical characteristics (continued)

Symbol	Parameter Test condition		Min.	Тур.	Max.	Unit
V <sub>BSUVHYS</sub>	V <sub>BS</sub> supply undervoltage lockout hysteresis	-	0.02	0.2	0.4	V
I <sub>QBS1</sub>	V <sub>BS</sub> supply current	static mode, V <sub>BS</sub> = 10 V, IN = 0 V or 5 V	-	-	100	μА
I <sub>QBS2</sub>	VBS Supply current	static mode, V <sub>BS</sub> = 18 V, IN = 0 V or V <sub>CC</sub>	-	-	200	μА
$\Delta V_{BS}$	V <sub>BS</sub> drop due to output turn-on	$V_{BS}$ = 17 V, $C_{BS}$ = 1 μF, $td_{IG-IN}$ = 3 μs, $t_{TEST}$ = 100 μs	-	-	210	mV
Gate drive	er characteristics					
I <sub>PKSo1</sub>		$V_{BS} = 10 \text{ V}$ , $T_j = 25 \text{ °C}$ $PW \le 10  \mu\text{s}$	120	250	-	
I <sub>PKSo2</sub>	Peak output source current	V <sub>BS</sub> = 10 V PW ≤ 10 μs	70	150	-	m 1
I <sub>PKSo3</sub>		$V_{BS}$ = 17 V, $T_j$ = 25 °C PW $\leq$ 10 $\mu s$	250	500	-	mA
I <sub>PKSo4</sub>		$V_{BS} = 17 \text{ V},$ PW $\leq 10  \mu\text{s}$	150	300	-	
I <sub>HOH,off</sub>	HOH off-state leakage current Guaranteed by design		-	-	1	μΑ
t <sub>r1</sub>		$V_{BS} = 10 \text{ V}, T_j = 25^{\circ}\text{C}$	-	0.2	0.4	
t <sub>r2</sub>	Output rise time	V <sub>BS</sub> = 10 V	-	0.3	0.5	μS
t <sub>r3</sub>	Output rise time	$V_{BS} = 17 \text{ V}, T_j = 25 ^{\circ}\text{C}$	-	0.1	0.2	μο
t <sub>r4</sub>		V <sub>BS</sub> = 17 V	-	0.15	0.3	
I <sub>PKSi1</sub>		$\begin{split} &\text{IN} = \text{V}_{CC},  \text{T}_j = 25 ^{\circ}\text{C} \\ &\text{V}_{BS} = 10  \text{V},  \text{PW} < 10  \mu\text{s} \end{split}$	120	250	-	
I <sub>PKSi2</sub>	Pook output sink ourrent	$\begin{split} &IN = V_{CC}, \\ &V_{BS} = 10V \;, \; PW < 10 \; \mu s \end{split}$	70	150	-	m 1
I <sub>PKSi3</sub>	Peak output sink current	$\begin{split} &\text{IN} = \text{V}_{\text{CC}},  \text{T}_{j} = 25  ^{\circ}\text{C} \\ &\text{V}_{\text{BS}} = 17  \text{V},  \text{PW} < 10   \mu\text{s} \end{split}$	250	500	-	mA
I <sub>PKSi4</sub>		$\begin{split} &\text{IN} = \text{V}_{\text{CC}}, \\ &\text{V}_{\text{BS}} = 17 \text{ V, PW} < 10  \mu\text{s} \end{split}$	150	300	-	
t <sub>f1</sub>		$V_{BS} = 10 \text{ V}, T_j = 25 ^{\circ}\text{C}$	-	0.2	0.4	
t <sub>f2</sub>	Output fall time	V <sub>BS</sub> = 10 V	-	0.3	0.5	
t <sub>f3</sub>	Output fail tiffle	V <sub>BS</sub> = 17 V, T <sub>j</sub> = 25 °C	-	0.1	0.2	μS
t <sub>f4</sub>		V <sub>BS</sub> = 17 V	-	0.15	0.3	
t <sub>plh</sub>	Input-to-output turn-on propogation delay (50 % input level to 10 % output level)	-	-	0.1	0.3	μs

Table 6. Electrical characteristics (continued)

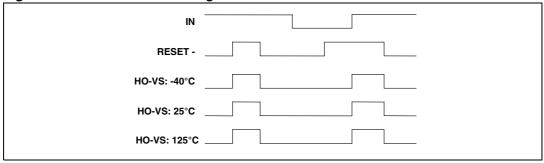
<b>Typ.</b> 0.1	lin.	<b>Max.</b> 0.2	Unit	
	-	0.2		
0.1				
RES-to-output turn-off propogation delay (50% input level to 90% - 0.1 0.1 output levels)		0.3	μS	
0.1	-	0.8		
	·			
-	9.5	-	V	
-	-	- 6		
-	60	300	kΩ	
-	-	5	μА	
-	3.5	-	V	
-	-	1.4	V	
-	60	300	kΩ	
-	-	5	μА	
	- 60 - 3.5	0.1	6 - 300 - 5 1.4 - 300	

<sup>1. 4</sup> HS-driver reset- inputs and other IC with their input pull-down resistors are connected in parallel with the RESET wire. The enable input RES- is an active low input, that means a logic low turns the external Power MOSFET off. The input circuitry has to make sure, that the MOSFET is off, when the pin is open or floating. In the application the RES- pin is tied to a bipolar open collector transistor or MOSFET open drain transistor with pull-up resistor 3.8K to +5V together with other RES- inputs of other IC.

### 2.5 Reset functional diagram

The diagram is guaranteed for the following condition.  $V_{CC}$  = 10 V;  $V_{BS}$  = 10 V @ -40 °C,  $V_{CC}$  = 17 V;  $V_{BS}$  = 17 V @ +25 °C and 125 °C

Figure 3. Reset functional diagram



Timing diagrams L9857

## 3 Timing diagrams

8/11

Figure 4. Input/output timing diagram

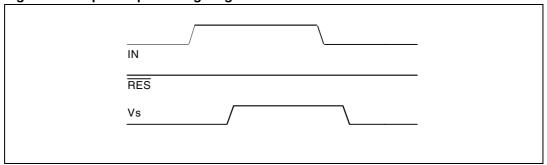
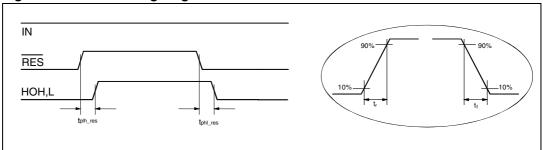


Figure 5. Reset timing diagram



L9857 Package information

## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: <a href="https://www.st.com">www.st.com</a>. ECOPACK<sup>®</sup> is an ST trademark.

Figure 6. SO-8 mechanical data and package dimensions

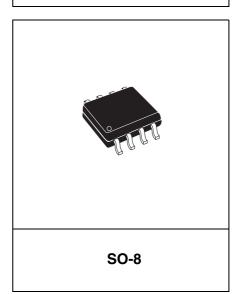
DIM.	mm		inch			
DIIVI.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
Α			1.750			0.0689
A1	0.100		0.250	0.0039		0.0098
A2	1.250			0.0492		
b	0.280		0.480	0.0110		0.0189
С	0.170		0.230	0.0067		0.0091
D (1)	4.800	4.900	5.000	0.1890	0.1929	0.1969
E	5.800	6.000	6.200	0.2283	0.2362	0.2441
E1 <sup>(2)</sup>	3.800	3.900	4.000	0.1496	0.1535	0.1575
е		1.270			0.0500	
h	0.250		0.500	0.0098		0.0197
L	0.400		1.270	0.0157		0.0500
L1		1.040			0.0409	
k	0°		8°	0°		8°
ccc			0.100			0.0039
Notes: 1.	Dimensi	ons D do	es not inc	lude mold	flash.	•

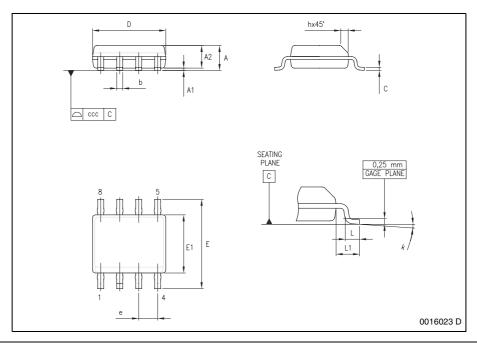
Notes: 1. Dimensions D does not include mold flash, protrusions or gate burrs.

Mold flash, potrusions or gate burrs shall not exceed 0.15mm in total (both side).

2. Dimension "E1" does not include interlead flash

# OUTLINE AND MECHANICAL DATA





<sup>exceed 0.15mm in total (both side).
2. Dimension "E1" does not include interlead flash</sup> or protrusions. Interlead flash or protrusions shall not exceed 0.25mm per side.

Revision history L9857

## 5 Revision history

Table 7. Document revision history

Date	Revision	Changes	
20-Nov-2006	1	Initial release.	
07-Oct-2009	2	Updated Table 1: Device summary.	

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